



Material Content Data Sheet



Sales Product Name		BSP179 H6327		Issued		19. January 2018		
MA#		MA001345810						
Package		PG-SOT223-4-21		Weight*		113.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.037	0.03		323	
	non noble metal	tin	7440-31-5	0.009	0.01		83	
	inorganic material	silicon	7440-21-3	0.416	0.37	0.41	3660	4066
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		447	
	non noble metal	chromium	7440-47-3	0.152	0.13		1340	
	non noble metal	copper	7440-50-8	50.489	44.47	44.65	444708	446584
wire	non noble metal	copper	7440-50-8	0.020	0.02	0.02	178	178
encapsulation	organic material	carbon black	1333-86-4	0.604	0.53		5316	
	plastics	epoxy resin	-	9.053	7.97		79740	
	inorganic material	silicondioxide	60676-86-0	50.697	44.66	53.16	446542	531598
leadfinish	non noble metal	tin	7440-31-5	1.482	1.31	1.31	13056	13056
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4518	4518
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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